Product End-of-Life Disassembly Instructions

Product Category: Servers
Marketing Name / Model **[List multiple models if applicable.]**
HP CloudLine CL1100 G3 208S

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	**Notes**	**Quantity of items included in product**
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sqcm	5
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	1 super cap in LSI9271-8i Card and 1 in PSU	2
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardantsweighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing		0

refractory ceramic fibers		
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	**Tool Size (if applicable)**
Philips Driver	#2
Flat Head Screw Driver	Medium

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. System Board Battery -- Remove the top cover and locate the battery on the system board. With a medium flat headscrew driver remove the battery and dispose of properly.
2. Super Cap for LSI9271-8i Card -- Remove the top cover and locate the Super Cap in the chassis. With a medium flat head screw driver remove the Super Cap and dispose of properly.
3. Capacitors > 2.5CM -- Remove the power supply(s) from the system. With screw driver, remove the screws securing the top cover,locate the capacitors and pry from the PCB with a medium flat head screw driver and dispose of properly.
4.
5.
6.
7.
8.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Attachment 1-- System battery location

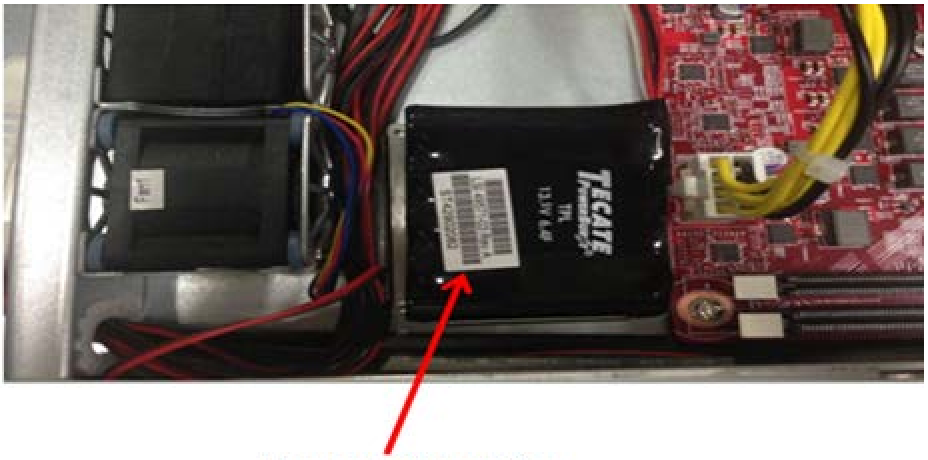
Attachment 2-- Super Cap For LSI9271-8i Card Location

Attachment 3-- Super Capacitors Location in PSU

Attachment 1

Remove Battery

Attachment 2



Remove Super Cap

Attachment 3

Model:EP1A4551A-P4RA

Remove capacitor